

# QT-Brightek Chip LED Series

## SMD 0805 LED

Part No.: QBLP631-YG

**Table of Contents:**

Introduction .....	3
Electrical / Optical Characteristic (Ta=25 °C) .....	4
Absolute Maximum Rating .....	4
Characteristic Curves.....	5
Solder Profile & Footprint.....	6
Packing .....	7
Labeling .....	8
Ordering Information.....	9
Revision History .....	10
Disclaimer .....	10

## Introduction

**Feature:**

- Water clear lens (except white color)
- Package in tape and reel
- Bright 0805 LED package
- GaP Technology

**Description:**

These ultra bright 0805 LEDs have a height profile of 0.8mm. Combination of high brightness output and small footprint, these LEDs are ideal for keypad backlighting and status indication.

**Application:**

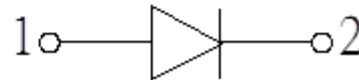
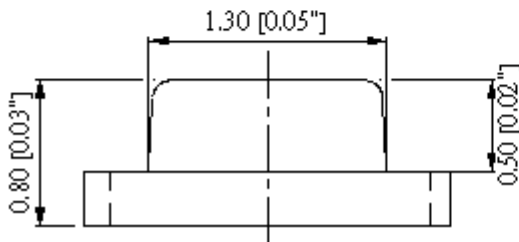
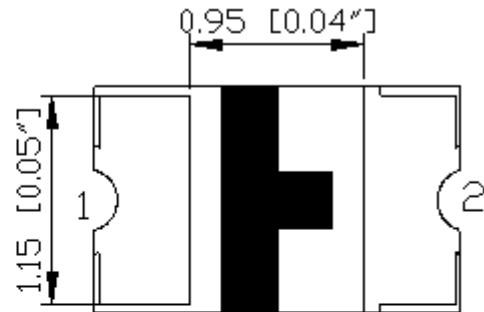
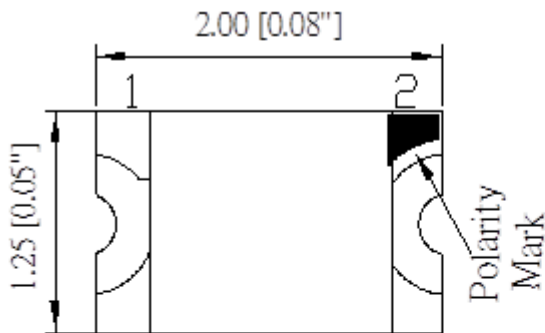
- Status indication
- Back lighting application

**Certification & Compliance:**

- TS16949
- ISO9001
- RoHS Compliant



**Dimension:**



Units: mm / tolerance = +/-0.1mm

**Electrical / Optical Characteristic (Ta=25 °C)**

Product	Color	I <sub>F</sub> (mA)	V <sub>F</sub> (V)		λ <sub>D</sub> (nm)			I <sub>V</sub> (mcd)	
			Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.
QBLP631-YG	Yellow Green	20	2.0	2.5	565	570	576	5.0	15

**Absolute Maximum Rating**

Material	P <sub>d</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)*	V <sub>R</sub> (V)	T <sub>OP</sub> (°C)	T <sub>ST</sub> (°C)	T <sub>SOL</sub> (°C)**
GaP	75	30	125	5	-40 ~ +80	-40 ~ +85	260

\*Duty 1/8 @ 1KHz

\*\*IR Reflow for no more than 10 sec @ 260 °C

**Forward Voltage V<sub>F</sub> for GaP @ I<sub>F</sub>=20mA**

Bin	Min.	Max.	Unit
□	1.7	2.5	V

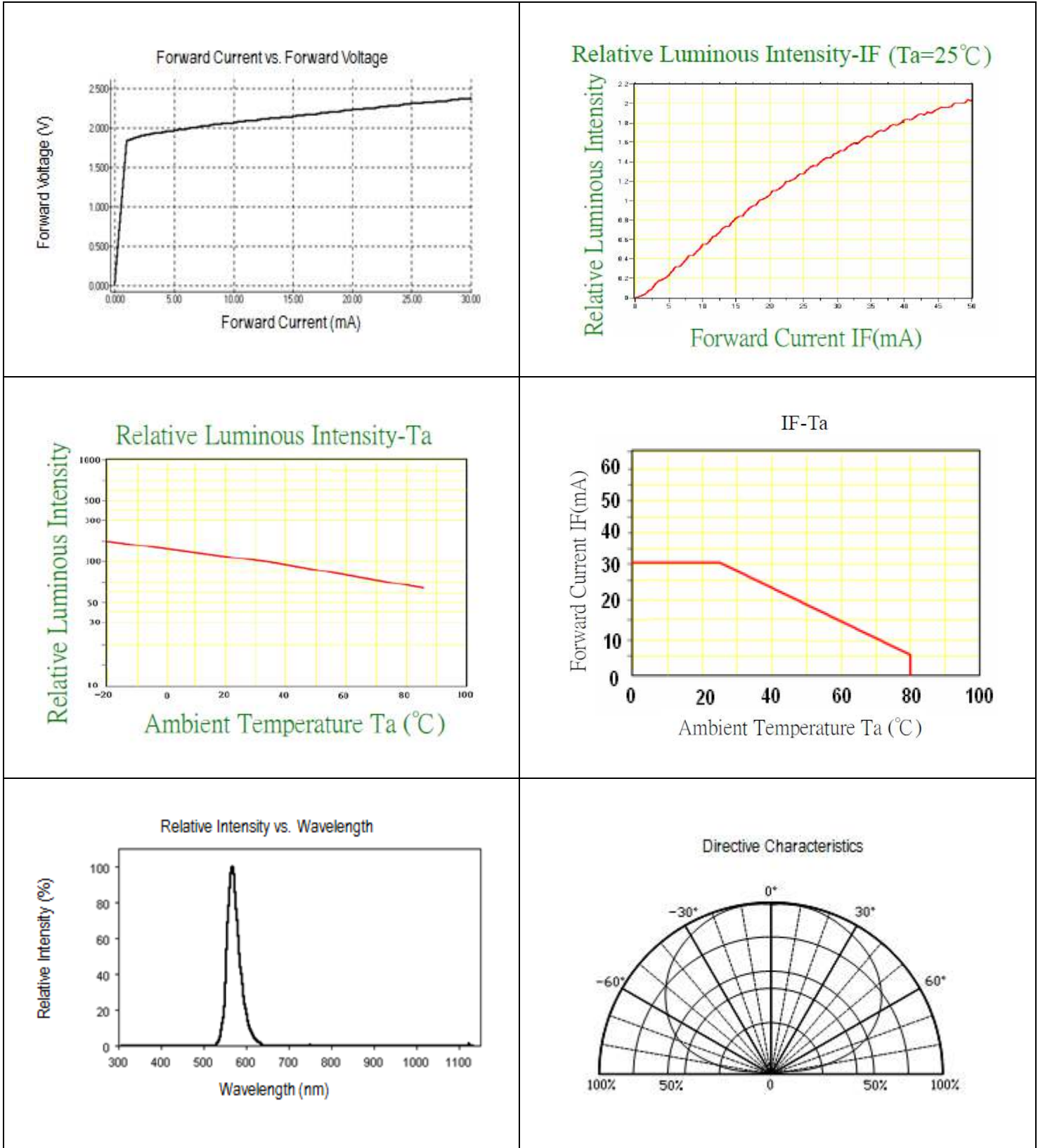
**Luminous Intensity I<sub>V</sub> @ I<sub>F</sub>=20mA**

Bin	Min.	Max.	Unit
8	5.0	8.0	mcd
9	8.0	12.5	
A	12.5	16	
B	16	20	
C	20	25	

**Dominant Wavelength λ<sub>D</sub> for Yellow Green @ I<sub>F</sub>=20mA**

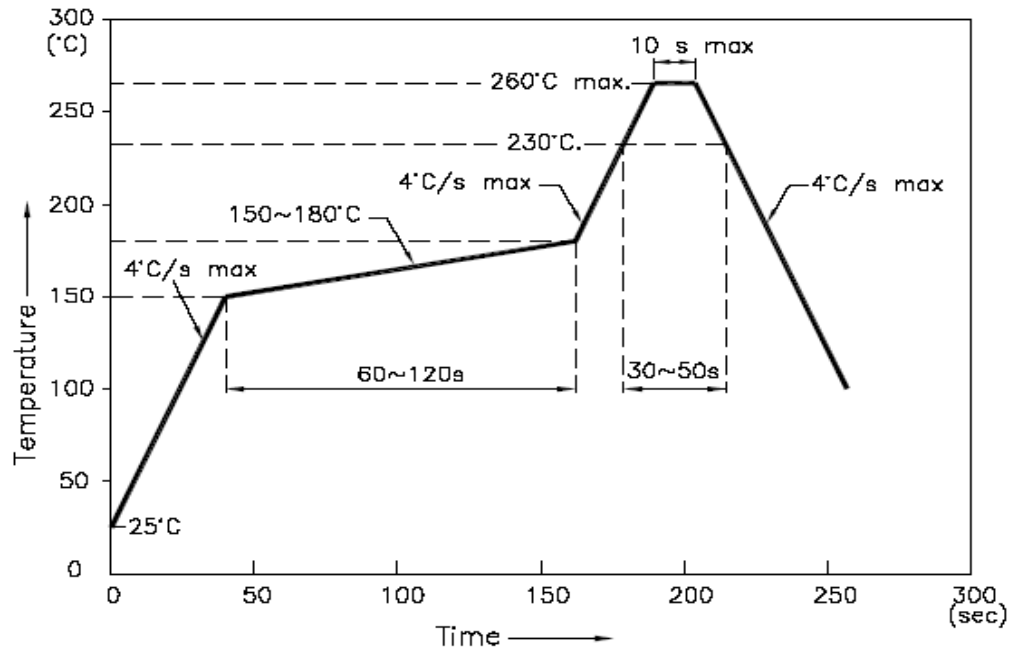
Bin	Min.	Max.	Unit
h	565	568	nm
i	568	572	
j	572	576	

**Characteristic Curves**

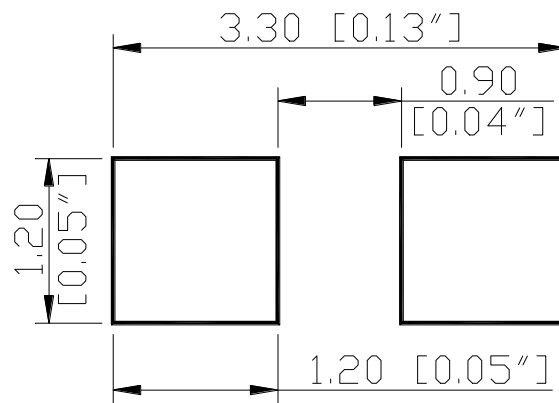


## Solder Profile & Footprint

- Recommended tin solder specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



### Recommended Pad Layout

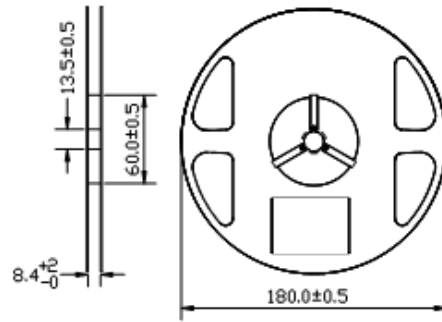


Units: mm

Tolerance: ± 0.1mm

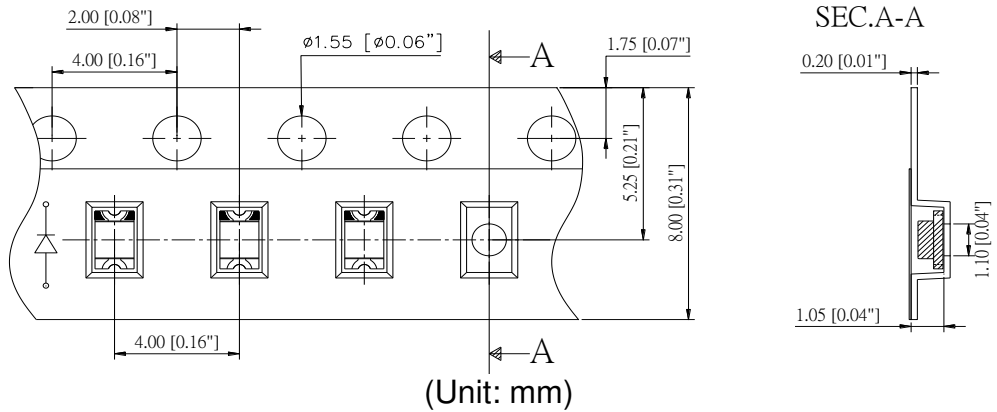
## Packing

Reel Dimension:



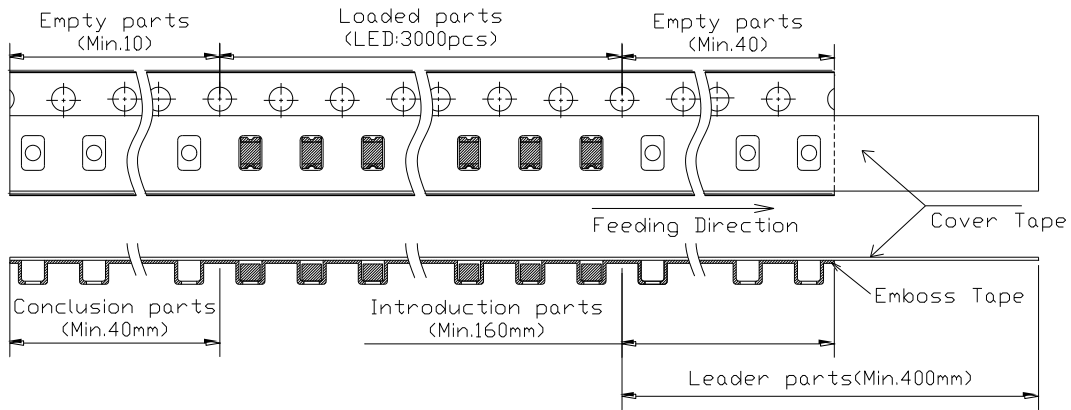
(Unit: mm)

Tape Dimension:

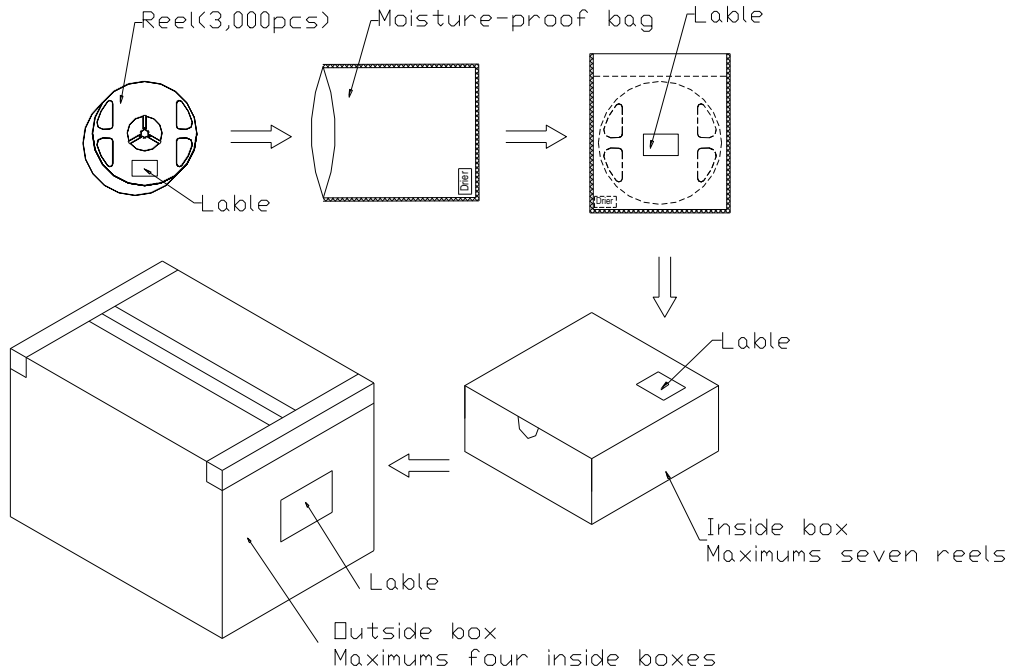


(Unit: mm)

Arrangement of Tape:



Packaging Specifications:



**Labeling**



**Part No:** \_\_\_\_\_

**Customer P/N:** \_\_\_\_\_

**Item:** \_\_\_\_\_

**Q'ty:** \_\_\_\_\_

**Vf:** \_\_\_\_\_

**Iv:** \_\_\_\_\_

**WI:** \_\_\_\_\_

**Date:** \_\_\_\_\_

**Made in China**

Product: QBLP631-YG	Date: September 16, 2014	Page 8 of 10
	Version# 1.0	



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**Ordering Information**

Part #	Orderable Part #	Spec Range	Quantity per reel
QBLP631-YG	QBLP631-YG	I <sub>v</sub> =15mcd typ. @ I <sub>F</sub> =20mA, λ <sub>D</sub> =565nm to 576nm	3,000 units

**Revision History**

Description:	Revision #	Revision Date
New Release of QBLP631-YG	V1.0	09/16/2014

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.